

Abstract

A phosphor-containing sheet having a storage modulus of 0.1 MPa or more at 25°C and a storage modulus of less than 0.1 MPa at 100°C, wherein a resin main component of the phosphor-containing sheet is a crosslinked product formed by subjecting a crosslinkable silicone composition containing a specific composition to a hydrosilylation reaction. This phosphor-containing sheet provides a phosphor sheet having good shapability and high adhesive power as a phosphor sheet bonded to an LED chip as a wavelength conversion layer.